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APPLICATION NO.	FILING DATE		FIRST NAMED INVENTOR	₹	ATTORNEY DOCKET NO.
09/768.580	01/23/01	мсманом		J	42390.P5142D
			_	٦ [EXAMINER
מוחעבוע פו	OKOLOFF. TAY	MMC1/0 LOR & ZAFM		СНА	MBLISS.A
SEVENTH FL				[ART UNIT PAPER NUMBER
12400 WILS	SHIRE BOULEV 5 CA 90025-1			2814	4
	-				DATE MAILED: 08/13/01

Please find below and/or attached an Office communication concerning this application or proceeding.

Commissioner of Patents and Trademarks

, 61		Application No.	Applicant(s)				
—		09/768,580	MCMAHON, JOHN F.				
*	Office Action Summary	Examiner	Art Unit				
		Alonzo Chambliss	2814				
	- The MAILING DATE of this communication ap	pears on the cover sheet	with the correspondence address				
Period for	r Reply						
THE N - Exten after S - If the - If NO - Failur - Any re earne	DRTENED STATUTORY PERIOD FOR REPL MAILING DATE OF THIS COMMUNICATION. sions of time may be available under the provisions of 37 CFR 1. SIX (6) MONTHS from the mailing date of this communication. period for reply specified above is less than thirty (30) days, a reperiod for reply is specified above, the maximum statutory period to to reply within the set or extended period for reply will, by statutionary received by the Office later than three months after the mailing d patent term adjustment. See 37 CFR 1.704(b).	136(a). In no event, however, may by within the statutory minimum of t will apply and will expire SIX (6) M	a reply be timely filed hirty (30) days will be considered timely. ONTHS from the mailing date of this communication. ABANDONED (35 U.S.C. § 133).				
Status 4\⊠	Responsive to communication(s) filed on 23	January <u>2001</u> .					
1)⊠ 2a)⊟	· · · · · · · · · · · · · · · · · · ·	his action is non-final.					
3)□	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.						
Dispositi	on of Claims						
	Claim(s) 1-27 is/are pending in the application						
	4a) Of the above claim(s) 1-20 is/are withdraw	wn from consideration.					
5)	Claim(s) is/are allowed.						
6)⊠	Claim(s) <u>21-27</u> is/are rejected.						
	Claim(s) is/are objected to.						
8)[Claim(s) are subject to restriction and	or election requirement.					
Applicat	ion Papers		i				
9)⊠	The specification is objected to by the Exami	ner.					
10)⊠	The drawing(s) filed on 23 January 2001 is/a	re: a)□ accepted or b)⊠ o	objected to by the Examiner.				
	Applicant may not request that any objection to	the drawing(s) be held in al	Devance. See 37 CFR 1.85(a).				
11)	The proposed drawing correction filed on		_I alsapproved by the Examiner.				
ļ	If approved, corrected drawings are required in						
· ·	The oath or declaration is objected to by the	Examiner.					
	under 35 U.S.C. §§ 119 and 120		0 0 440(a) (d) == (0				
1	Acknowledgment is made of a claim for fore	eign priority under 35 U.S	.C. § 119(a)-(a) or (ī).				
a) All b) Some * c) None of:						
	1. Certified copies of the priority docume	ents have been received.					
	2. Certified copies of the priority docum	ents have been received	in Application No				
	3. Copies of the certified copies of the papplication from the International See the attached detailed Office action for a	Bureau (PC) Rule 17.2(a)).				
14)	Acknowledgment is made of a claim for dom	estic priority under 35 U.S	S.C. § 119(e) (to a provisional application).				
	a) The translation of the foreign language Acknowledgment is made of a claim for dom and the foreign language and the	provisional application h	as been received.				
	•	•					
2) 🗍 No	ent(s) htice of References Cited (PTO-892) htice of Draftsperson's Patent Drawing Review (PTO-948) formation Disclosure Statement(s) (PTO-1449) Paper No	5) Noti	view Summary (PTO-413) Paper No(s) ce of Informal Patent Application (PTO-152) er:				

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DETAILED ACTION

Information Disclosure Statement

1. The information disclosure statement submitted on 1/23/01 was filed before the mailing date of the non-final rejection on 7/24/01. The submission is in compliance with the provisions of 37 CFR 1.97. Accordingly, the petition is granted and the information disclosure statement is being considered by the examiner.

Drawings

2. The drawings are objected to as failing to comply with 37 CFR 1.84(p)(5) because they include the following reference sign(s) not mentioned in the description: 38, 52, 80, 102, 120, 122, 130, and 134. Correction is required.

Specification

3. The title of the invention is not descriptive. A new title is required that is clearly indicative of the invention to which the claims are directed. The following title is suggested: "METHOD OF FABRICATING A STACKED CHIP PACKAGE".

Claim Rejections - 35 USC § 112

4. The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

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5. Claims 23-25 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

- 6. Claims 23 and 25 recites the limitation " a second chip " in lines 2 and 1 respectively. There is insufficient antecedent basis for this limitation in the claim.
- 7. Claim 23 recites the limitation "a first chip " in line 1. There is insufficient antecedent basis for this limitation in the claim.

Claim Rejections - 35 USC § 102

8. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 9. Claims 21, 26, and 27 are rejected under 35 U.S.C. 102(b) as being anticipated by Kiyoshi (JP 4-219966).

With respect to Claim 21, Kiyoshi places a first chip package 4 on a first shelf, which is electrically attached to the first shelf. A second chip package 4 (i.e. the chip above the first chip package) is electrically attached to the second shelf (see English abstract and figures).

With respect to Claim 26, the first chip package 4 is wire bonded to the first shelf (see Fig. 1).

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With respect to Claim 27, the second chip package 4 is wire bonded to the second shelf by the substrate (see Fig. 1).

10. Claims 21, 26, and 27 are rejected under 35 U.S.C. 102(b) as being anticipated by Hsu (U.S. 5,633,530).

With respect to Claim 21, Hsu places a first chip package 13a on a first shelf, which is electrically attached to the first shelf. A second chip package 13b is electrically attached to the second shelf (see Fig.1).

With respect to Claim 26, the first chip package 13a is wire bonded to the first shelf (see Fig. 1).

With respect to Claim 27, the second chip package 13b is wire bonded to the second shelf by the substrate (see Fig. 1).

Claim Rejections - 35 USC § 103

- 10. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patent ability shall not be negative by the manner in which the invention was made.
- 11. Claims 22 and 23 are rejected under 35 U.S.C. 103(a) as being unpatentable over Hsu (U.S. 5,633,530) as applied to claim 21 above, and further in view of Chia et al. (U.S. 5,563,446).

Hsu disclose covering the package above the second chip package with a lid 16b (see Fig. 1). Hsu fails to disclose filling the package above the second chip package with an encapsulant. However, with respect to Claims 22 and 23, Chia discloses filling

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the package above a chip with an encapsulant 188 or a lid 288. The encapsulant when added to the package taught by Hsu would seal the open cavity below the second shelf to protect the first chip package. Therefore, it would be obvious to use the encapsulant taught by Chia instead of the lid taught by Hsu since the encapsulant would protect the die and its wire bond leads in the same conventional manner as the lid.

12. Claim 24 and 25 are rejected under 35 U.S.C. 103(a) as being unpatentable over Hsu (U.S. 5,633,530) as applied to claim 21 above, and further in view of Wenzel et al. (U.S. 6,150,724).

Hsu discloses two semiconductor chips one above the other (see Fig. 1). Hsu fails to disclose a CPU chip package on the first shelf and a memory cache on the second shelf. However, with respect to Claim 24 and 25, Wenzel discloses semiconductor chip can be made of the same process or different process. For example, the semiconductor chip can be a CPU, SDRAM, DRAM, etc. (see col. 6 lines 60-67 and col. 7 lines 1-18). Therefore, it would have been obvious to use the CPU and SDRAM chips as taught by Wenzel in the semiconductor package taught by Hsu since the combination of the CPU and the SDRAM would provide the semiconductor package with the ability to process data and store memory.

Conclusion

13. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. It is cited primarily to show processes of packaging a semiconductor device which are similar to the process of the instant invention.

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Any inquiry concerning the communication or earlier communications from the examiner should be directed to Alonzo Chambliss whose telephone number is (703) 306-9143. The fax phone number for this Group is (703) 308-7722 or 7724.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the Group receptionist whose telephone number is (703) 308-7956.

OLIK CHAUDHURI SUPERVISORY PATENT EXAMINER TECHNOLOGY CENTER 2800

AC/July 24, 2001